

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/14/2022

Details for "TPS71401DRVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS71401DRVR	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DRV 6	2x2x0.75	9.3

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.047324	100	1000000	0.51122	5112
Sub-Total			0.047324	100	1000000	0.51122	5112
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.076304	80	800000	0.824278	8243
Thermoplastics	Epoxy	85954-11-6	0.019076	20	200000	0.206069	2061
Sub-Total			0.09538	100	1000000	1.030347	10303
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	4.537285	97.596989	975970	49.014256	490143
Copper and Its Alloys	Iron	7439-89-6	0.103673	2.230006	22300	1.119933	11199
Copper and Its Alloys	Phosphorus	7723-14-0	0.001627	0.034997	350	0.017576	176
Zinc and Its Alloys	Zinc	7440-66-6	0.006416	0.138008	1380	0.069309	693
Sub-Total			4.649001	100	1000000	50.221074	502211
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.079901	95.120238	951202	0.863135	8631
Precious Metals	Gold	7440-57-5	0.000655	0.779762	7798	0.007076	71
Precious Metals	Palladium	7440-05-3	0.003444	4.1	41000	0.037204	372
Sub-Total			0.084	100	1000000	0.907414	9074
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	3.725076	90.49998	905000	40.240327	402403
Other Plastics and Rubber	Carbon Black	1333-86-4	0.020581	0.500011	5000	0.222327	2223
Thermoplastics	Epoxy	85954-11-6	0.37045	9.000009	90000	4.001805	40018
Sub-Total			4.116107	100	1000000	44.464459	444645
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.26526	100	1000000	2.865485	28655
Sub-Total			0.26526	100	1000000	2.865485	28655
Total			9.257072			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.